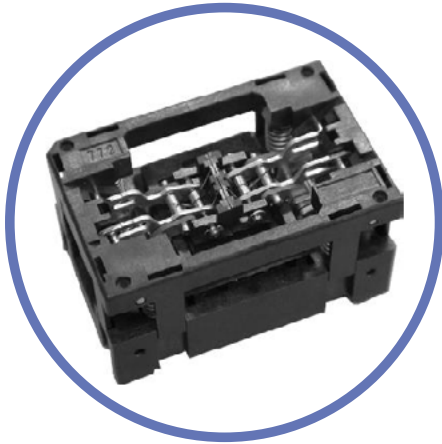


772 SERIES

OPEN TOP CSP



Features

- 0.4mm pitch for large array
- Compression surface mount
- Support up to 34x34 ball matrix
- Z-axis compliant buckling beam, contact provides stable contact performance independent of solder ball height and composition
- Sharpe edge of dual-point contact tip provides high electrical performance, minimizing ball damage
- Staggered fan out footprint for PCB design consideration
- Advanced latching system provide the ability to handle very thin package, limiting package wrap

MATERIALS AND SPECIFICATIONS

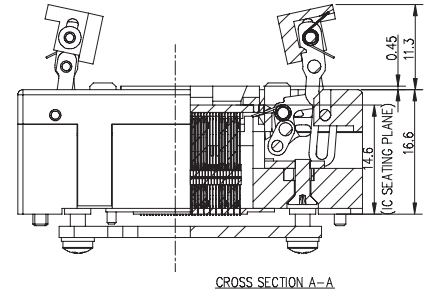
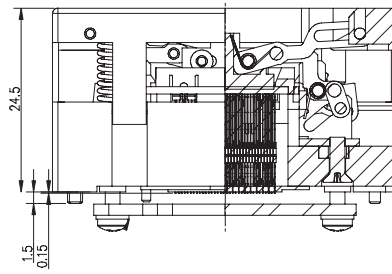
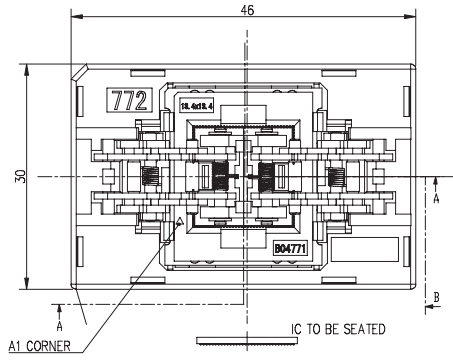
Body Materials	PES, PEI, LCP, or Equivalent
Contact Material	Beryllium Copper Alloy
Contact Plating	Gold
Contact Normal Force	13 gram average
Contact Resistance	200~300 mΩ
Capacitance	
Temperature Rating	150°C
Durability	10,000 cycles min.

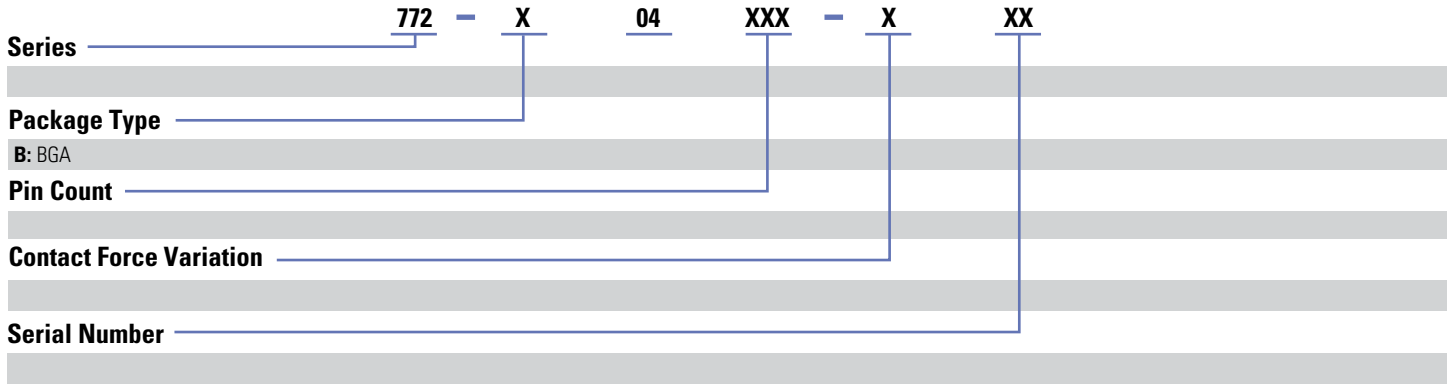
Pitch e (mm)	Package Size (mm)	Pin Matrix	Max. Pin Count	Ball Dia. (mm)	Ball Height (mm)	Part Number
0.4	6.2 x 12.6	14 x 30	420	0.25	0.17	772-B04420-XXX
	12.6 x 12.6	30 x 30	900	0.23	0.17	772-B04900-XXX
	13.4 x 13.4	32 x 32	1024	0.25	0.17	772-B041024-XXX
	14 x 14	33 x 33	1089	0.25	0.16	772-B041089-XXX



DIMENSIONS AND DIAGRAMS

Dimensions in mm





Revised 02/06/18

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